

# RJF0411JPD

40V, 34A Silicon N Channel  
Thermal FET Power Switching

R07DS1258EJ0100  
Rev.1.00  
Jun 23, 2015

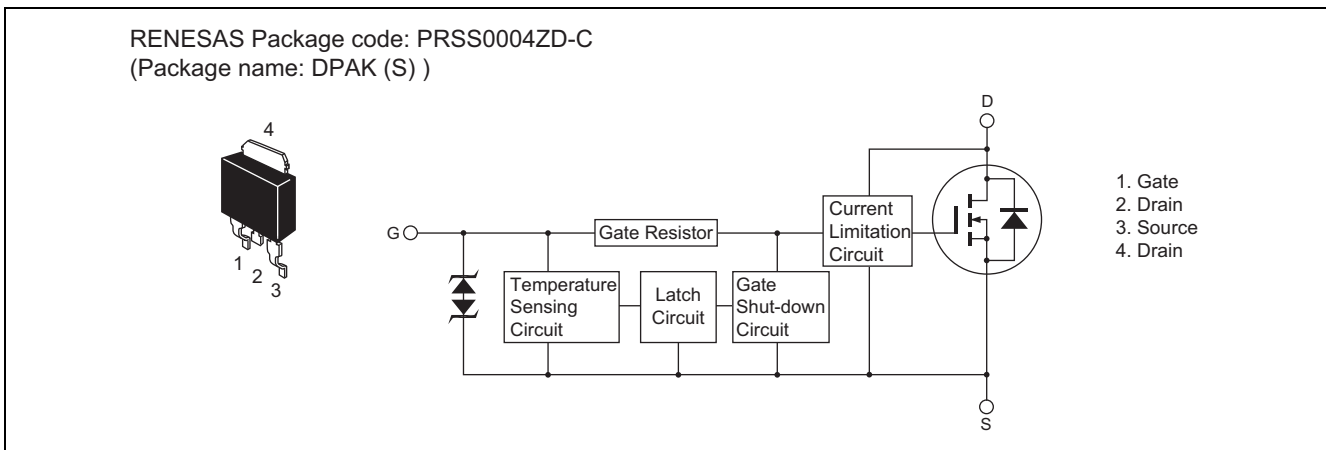
## Description

This FET has the over temperature shut-down capability sensing to the junction temperature. This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc..

## Features

- Logic level operation.
- Built-in the over temperature shut-down circuit.
- High endurance capability against to the short circuit.
- Latch type shut down operation (need 0 voltage recovery).
- Built-in the current limitation circuit.
- Power supply voltage applies 12 V.
- AEC-Q101 Compliant.
- Endurance capability against to ESD.

## Outline



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	40	V
Gate to source voltage	V <sub>GSS</sub>	16	V
Gate to source voltage	V <sub>GSS</sub>	-2.5	V
Drain current	I <sub>D</sub> <sup>Note3</sup>	34	A
Body-drain diode reverse drain current	I <sub>DR</sub>	34	A
Avalanche current	I <sub>AP</sub> <sup>Note 2</sup>	5	A
Avalanche energy	E <sub>AR</sub> <sup>Note 2</sup>	166	mJ
Channel dissipation	P <sub>ch</sub> <sup>Note 1</sup>	40	W
Channel temperature	T <sub>ch</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

- Notes: 1. Value at Tc = 25°C  
 2. T<sub>ch</sub> = 25°C, R<sub>g</sub> ≥ 50 Ω  
 3. It provides by the current limitation lower bound value.

## Typical Operation Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage	V <sub>IH</sub>	3.5	—	—	V	
	V <sub>IL</sub>	—	—	1.2	V	
Input current (Gate non shut down)	I <sub>IH1</sub>	—	—	100	μA	V <sub>i</sub> = 8 V, V <sub>DS</sub> = 0
	I <sub>IH2</sub>	—	—	50	μA	V <sub>i</sub> = 3.5 V, V <sub>DS</sub> = 0
	I <sub>IL</sub>	—	—	1	μA	V <sub>i</sub> = 1.2 V, V <sub>DS</sub> = 0
Input current (Gate shut down)	I <sub>IH(sd)1</sub>	—	0.8	—	mA	V <sub>i</sub> = 8 V, V <sub>DS</sub> = 0
	I <sub>IH(sd)2</sub>	—	0.35	—	mA	V <sub>i</sub> = 3.5 V, V <sub>DS</sub> = 0
Shut down temperature	T <sub>sd</sub>	—	175	—	°C	Channel temperature
Gate operation voltage	V <sub>op</sub>	3.5	—	12	V	
Drain current (Current limitation value)	I <sub>D limit</sub>	34	—	—	A	V <sub>GS</sub> = 5 V, V <sub>DS</sub> = 10 V <sup>Note 4</sup> T <sub>c</sub> ≤ 80°C

Note: 4. Pulse test

## Electrical Characteristics

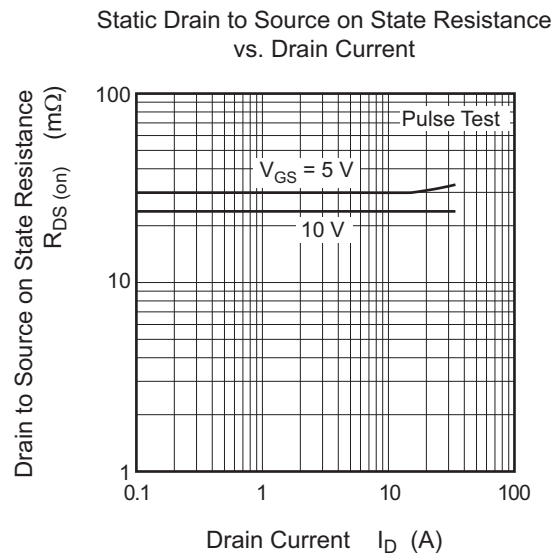
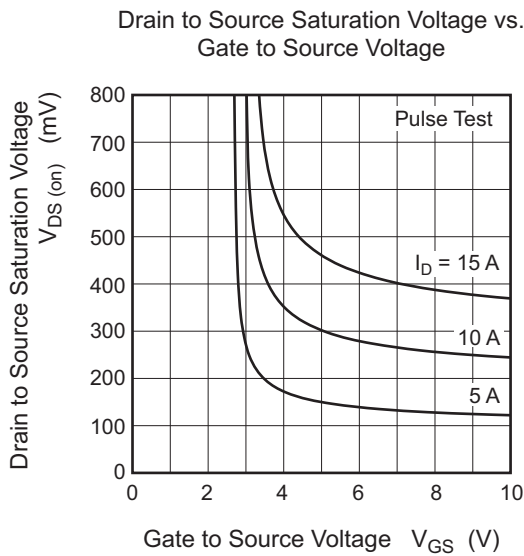
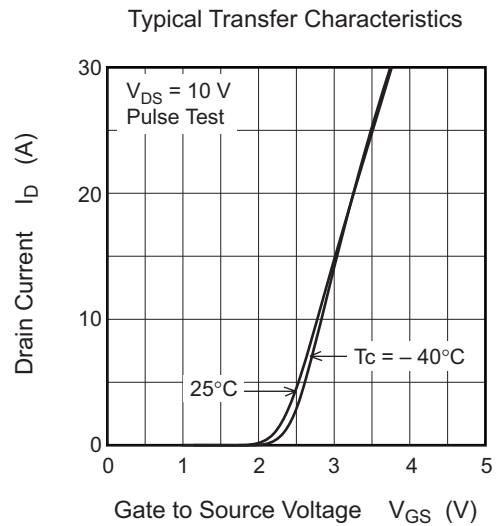
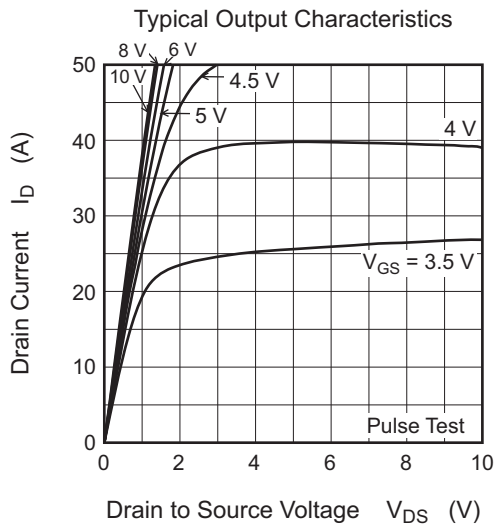
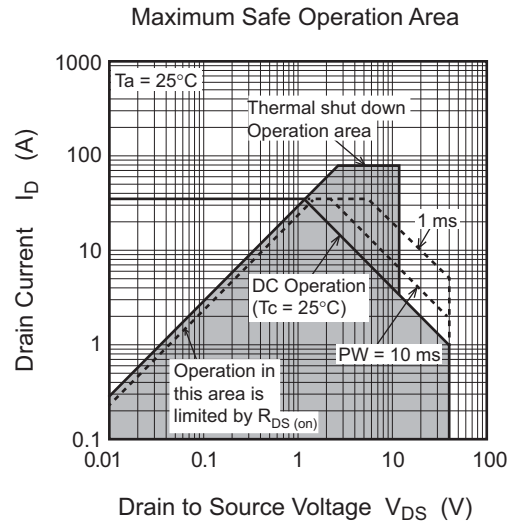
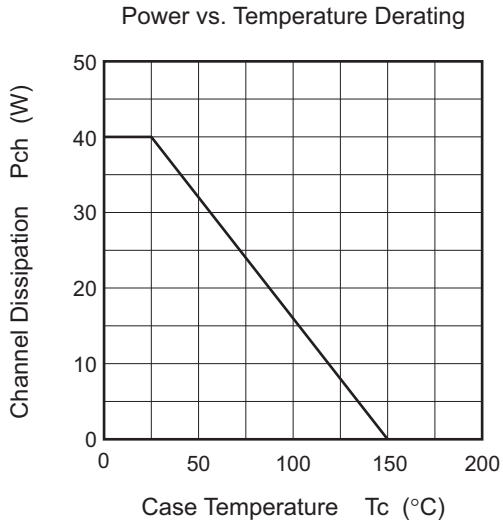
(Ta = 25°C)

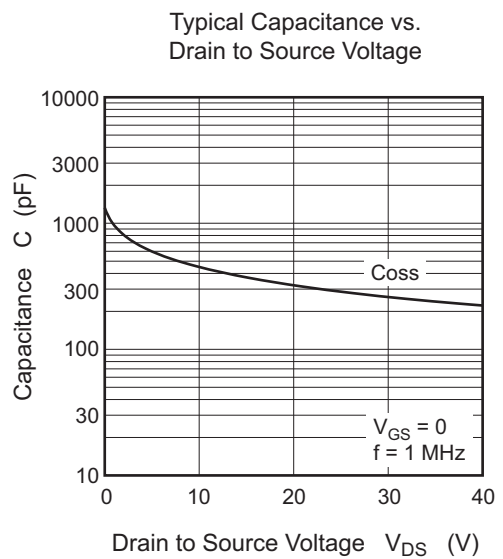
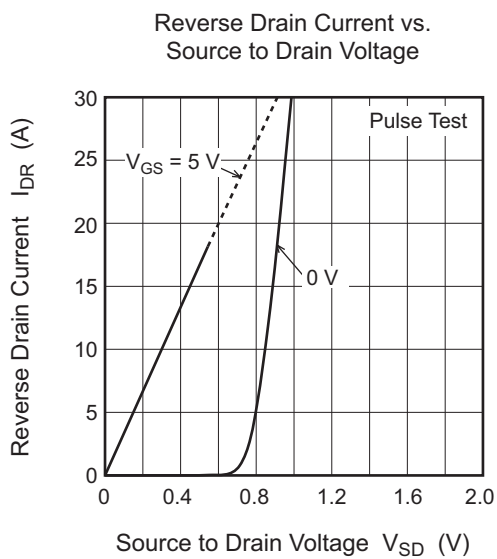
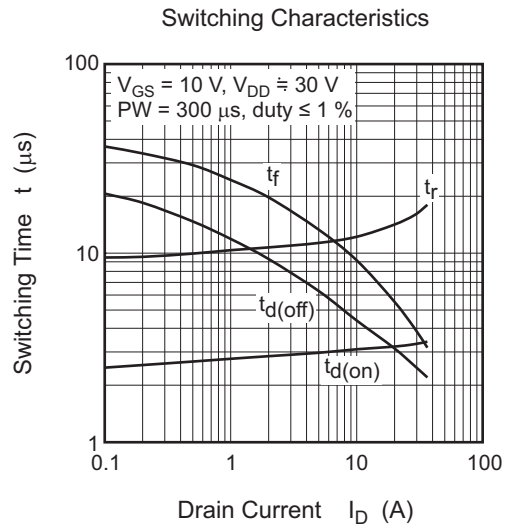
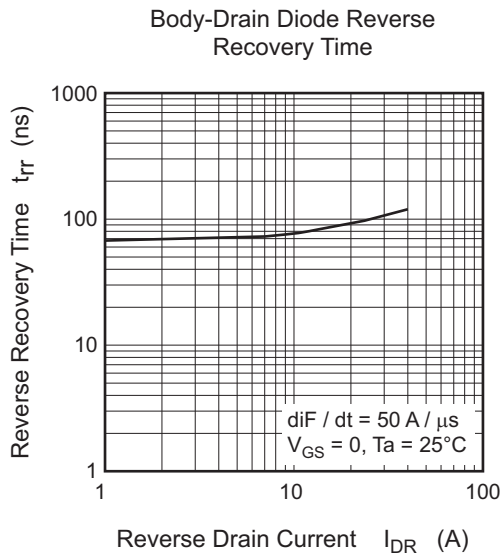
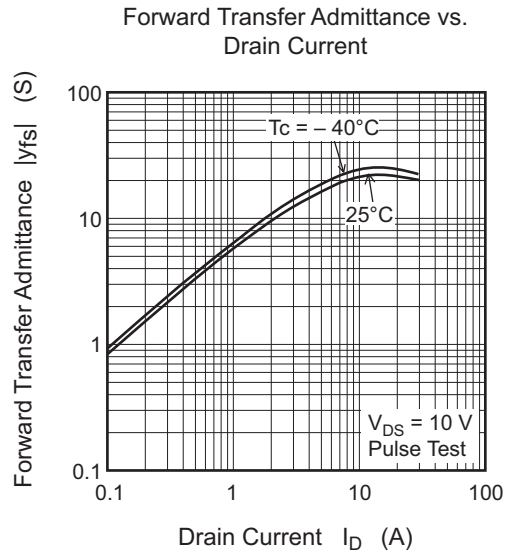
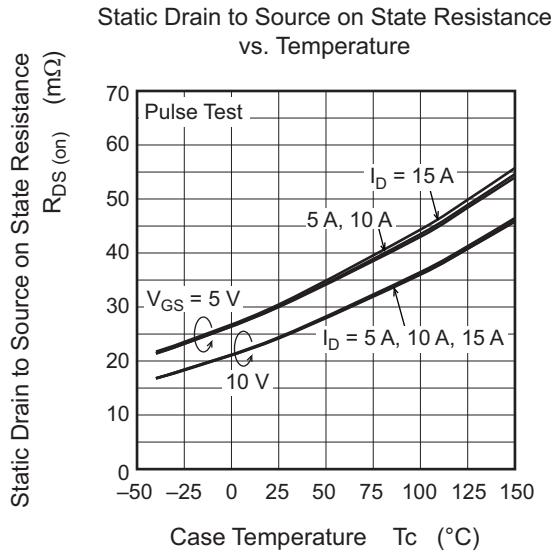
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain current	I <sub>D1</sub>	—	—	40	A	V <sub>GS</sub> = 3.5 V, V <sub>DS</sub> = 10 V <sup>Note 5</sup>
	I <sub>D2</sub>	—	—	10	mA	V <sub>GS</sub> = 1.2 V, V <sub>DS</sub> = 10 V
	I <sub>D3</sub>	34	—	—	A	V <sub>GS</sub> = 5 V, V <sub>DS</sub> = 10 V <sup>Note 5</sup> T <sub>c</sub> ≤ 80°C
	I <sub>D4</sub>	34	—	—	A	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V <sup>Note 5</sup> T <sub>c</sub> ≤ 80°C
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	40	—	—	V	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0
Gate to source breakdown voltage	V <sub>(BR)GSS</sub>	16	—	—	V	I <sub>G</sub> = 800 μA, V <sub>DS</sub> = 0
	V <sub>(BR)GSS</sub>	-2.5	—	—	V	I <sub>G</sub> = -100 μA, V <sub>DS</sub> = 0
Gate to source leak current	I <sub>GSS1</sub>	—	—	100	μA	V <sub>GS</sub> = 8 V, V <sub>DS</sub> = 0
	I <sub>GSS2</sub>	—	—	50	μA	V <sub>GS</sub> = 3.5 V, V <sub>DS</sub> = 0
	I <sub>GSS3</sub>	—	—	1	μA	V <sub>GS</sub> = 1.2 V, V <sub>DS</sub> = 0
	I <sub>GSS4</sub>	—	—	-100	μA	V <sub>GS</sub> = -2.4 V, V <sub>DS</sub> = 0
Input current (shut down)	I <sub>GS(OP)1</sub>	—	0.8	—	mA	V <sub>GS</sub> = 8 V, V <sub>DS</sub> = 0
	I <sub>GS(OP)2</sub>	—	0.35	—	mA	V <sub>GS</sub> = 3.5 V, V <sub>DS</sub> = 0
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	10	μA	V <sub>DS</sub> = 32 V, V <sub>GS</sub> = 0, T <sub>c</sub> = 110°C
Gate to source cutoff voltage	V <sub>GS(off)</sub>	1.1	—	2.1	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA
Forward transfer admittance	y <sub>fs</sub>	12	21.9	—	S	I <sub>D</sub> = 15 A, V <sub>DS</sub> = 10 V <sup>Note 5</sup>
Static drain to source on state resistance	R <sub>DS(on)</sub>	—	29.9	43	mΩ	I <sub>D</sub> = 15 A, V <sub>GS</sub> = 5 V <sup>Note 5</sup>
	R <sub>DS(on)</sub>	—	23.8	37	mΩ	I <sub>D</sub> = 15 A, V <sub>GS</sub> = 10 V <sup>Note 5</sup>
Output capacitance	C <sub>oss</sub>	—	416	—	pF	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1MHz
Turn-on delay time	t <sub>d(on)</sub>	—	3	—	μs	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, R <sub>L</sub> = 2 Ω
Rise time	t <sub>r</sub>	—	12.8	—	μs	
Turn-off delay time	t <sub>d(off)</sub>	—	4	—	μs	
Fall time	t <sub>f</sub>	—	9.9	—	μs	
Body-drain diode forward voltage	V <sub>DF</sub>	—	0.96	—	V	
Body-drain diode reverse recovery time	t <sub>rr</sub>	—	109	—	ns	I <sub>F</sub> = 30 A, V <sub>GS</sub> = 0 di <sub>F</sub> /dt = 50 A/μs
Over load shut down operation time <sup>Note 6</sup>	t <sub>os1</sub>	—	0.26	—	ms	V <sub>GS</sub> = 5 V, V <sub>DD</sub> = 16 V

Notes: 5. Pulse test

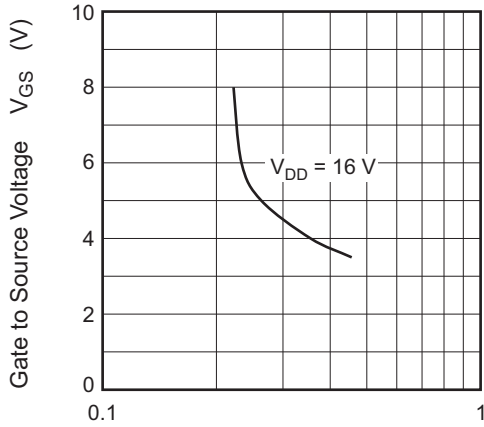
6. Including the junction temperature rise of the over loaded condition.

## Main Characteristics



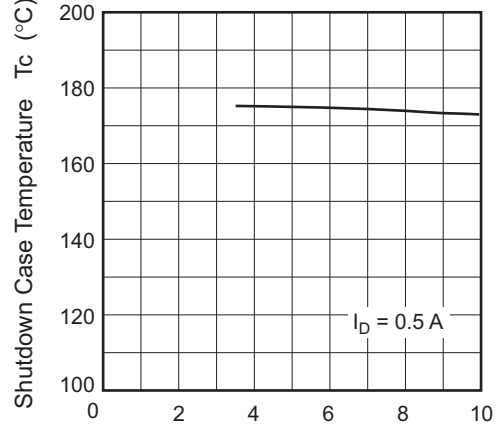


Gate to Source Voltage vs. Shutdown Time of Load-Short Test



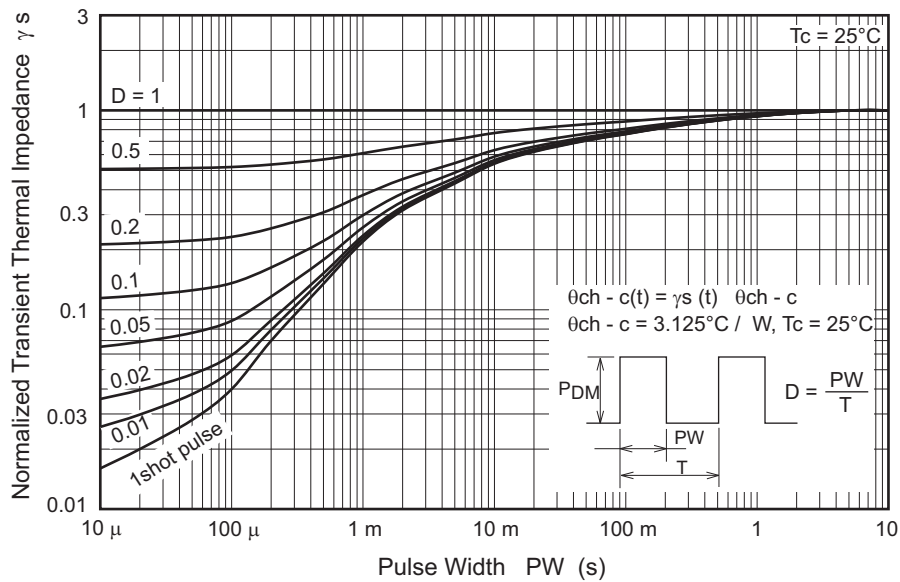
Shutdown Time of Load-Short Test PW (ms)

Shutdown Case Temperature vs. Gate to Source Voltage

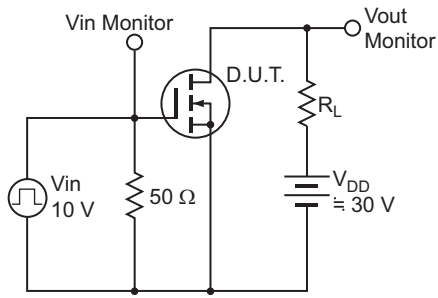


Gate to Source Voltage V\_GS (V)

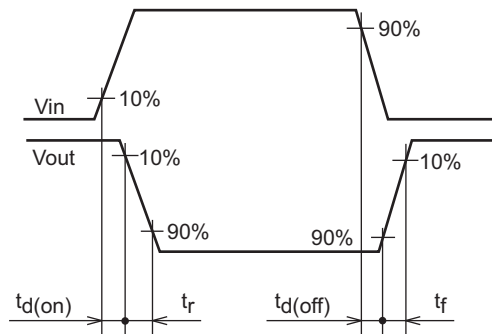
Normalized Transient Thermal Impedance vs. Pulse Width



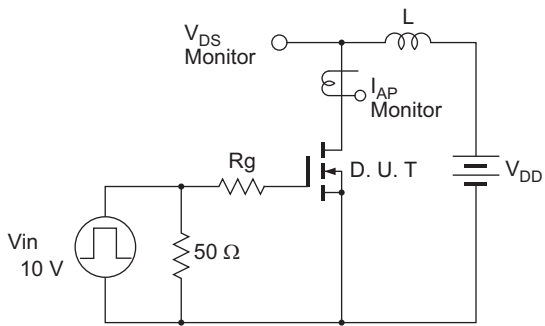
Switching Time Test Circuit



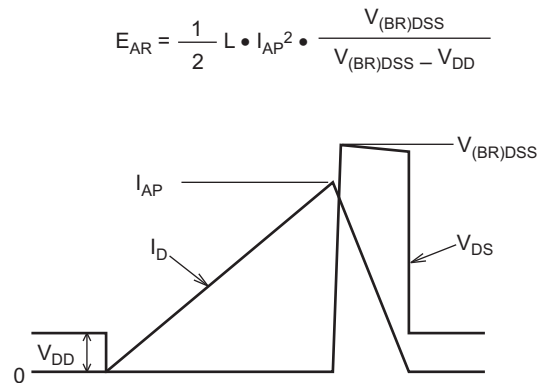
Waveform



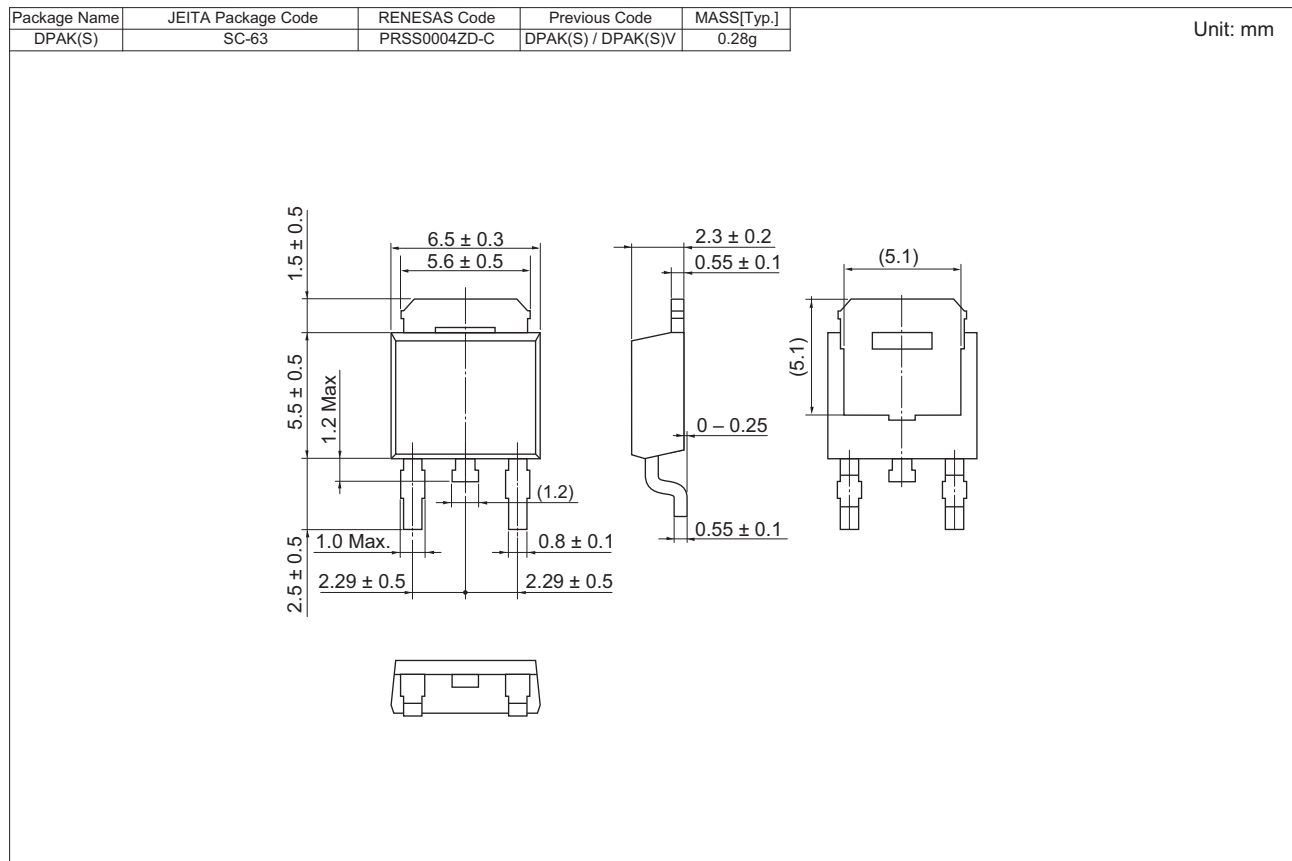
Avalanche Test Circuit



Avalanche Waveform



### Package Dimensions



### Ordering Information

Orderable Part Number	Quantity	Shipping Container
RJF0411JPD-00-J3	3000 pcs	Taping

Note: The symbol of 2nd "-" is occasionally presented as "#".

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